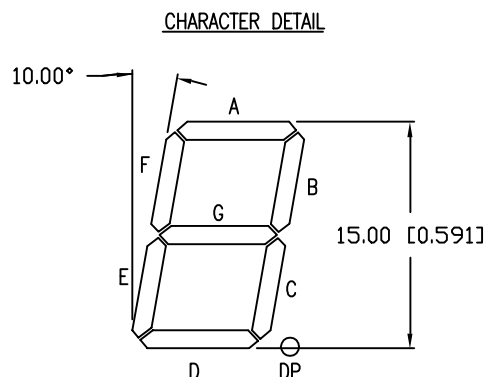
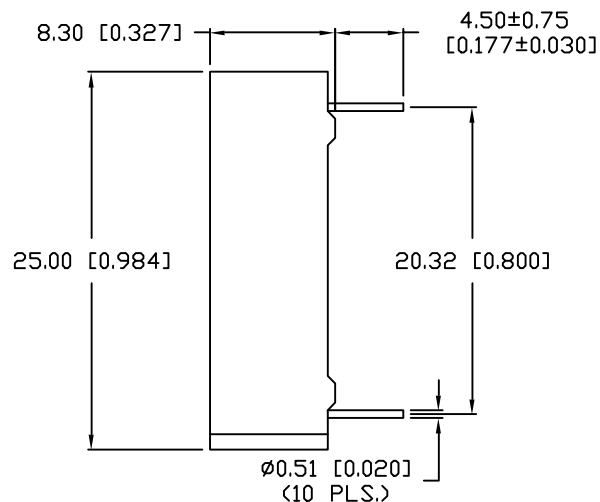
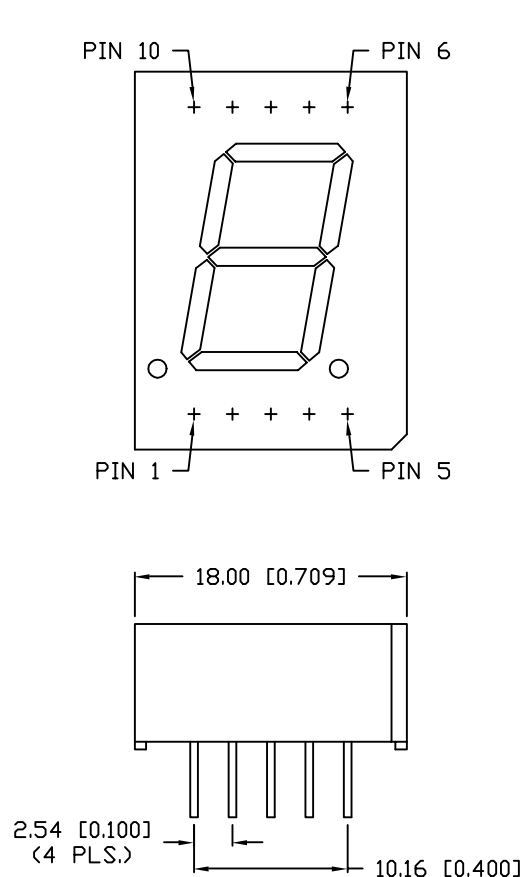


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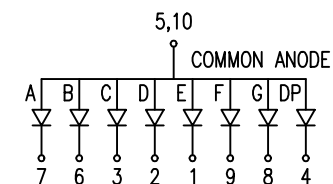
(LX)		PART NUMBER		REV.	
		LDS-A6006RI			
REV.	E.C.N. NUMBER AND REVISION COMMENTS			DATE	



ELECTRO-OPTICAL CHARACTERISTICS $T_A=25^\circ\text{C}$ $I_f=10\text{mA}$					
PARAMETER	MIN	TYP	MAX	UNITS	TEST COND
PEAK WAVELENGTH		660 (RED)		nm	
FORWARD VOLTAGE		1.7	2.3	V_f	
REVERSE VOLTAGE	5.0			V_r	$I_r=100\mu\text{A}$
AXIAL INTENSITY		13,000		μcd	$I_f=10\text{mA}$
EMITTED COLOR:	RED				
FACE COLOR:	GRAY				
SEGMENT COLOR:	MILKY WHITE DIFFUSED				

LIMITS OF SAFE OPERATION AT 25°C PER CHIP		
PARAMETER	MAX	UNITS
PEAK FORWARD CURRENT*	150	mA
STEADY CURRENT	30	mA
POWER DISSIPATION	105	mW
DERATE FROM 25°C	-1.2	mW/ $^\circ\text{C}$
OPERATING, STORAGE TEMP.	-40 TO +85	$^\circ\text{C}$
SOLDERING TEMP.	+260	$^\circ\text{C}$
2.0mm FROM BODY	3 SEC. MAX	


* $t < 10\mu\text{s}$



REPLACES PART #:LDS-A606RI

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*UNLESS OTHERWISE SPECIFIED TOLERANCE IS $\pm 0.25\text{mm}$ ($\pm 0.010''$)

REV.	PART NUMBER LDS-A6006RI	<div>CONFIDENTIAL INFORMATION</div> <div>THE INFORMATION CONTAINED IN THIS DOCUMENT IS THE PROPERTY OF LUMEX INC. EXCEPT AS SPECIFICALLY AUTHORIZED IN WRITING BY LUMEX INC., THE HOLDER OF THIS DOCUMENT SHALL KEEP ALL INFORMATION CONTAINED HEREIN CONFIDENTIAL AND SHALL PROTECT SAME IN WHOLE OR IN PART FROM DISCLOSURE AND DISSEMINATION TO ALL THIRD PARTIES.</div>	<div></div> <div>290 E. HELLEN ROAD PALATINE, ILLINOIS 60067 PHONE: 1-847-359-2790 WEB: HTTP://WWW.LUMEX.COM</div>
0.60" SINGLE DIGIT, SEVEN SEGMENT DISPLAY, 660nm RED CHIPS WITH GRAY FACE, MILKY WHITE DIFFUSED SEGMENTS, COMMON ANODE.		<div>RELIABILITY NOTE</div> <div>OUR MANY YEARS OF EXPERIENCE DATA ACCUMULATION INDICATE THAT SOLDER HEAT IS A MAJOR CAUSE OF EARLY AND FUTURE FAILURE. PLEASE PAY ATTENTION TO YOUR SOLDERING PROCESS.</div>	<div>DRAWN BY: SS/BC</div> <div>CHECKED BY:</div> <div>APPROVED BY:</div> <div>DATE: 1-25-99 PAGE: 1 OF 1 SCALE: N/A</div>

RELIABILITY NOTE
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